Supplementary Information for

Nanostructural Changes in Crystallizable Controlling Units Determine the Temperature-Memory of Polymers †

By Ulrich Nöchel^{a#}, Chaganti Srinivasa Reddy^{a#‡}, Ke Wang^{a§}, Jing Cui^{a+}, Ivo Zizak^b, Marc Behl^a, Karl Kratz^a and Andreas Lendlein^{a,c}*

^a Institute of Biomaterial Science, Helmholtz-Zentrum Geesthacht, Kantstraße 55, 14513 Teltow, Germany. e-mail: andreas.lendlein@hzg.de

^b Helmholtz-Zentrum Berlin, Institute for Nanometer Optics and Technology, Albert-Einstein-Str. 15, 12489 Berlin, Germany

^c Institute of Chemistry, University Potsdam, Karl-Liebknecht-Str. 24-25, 14476 Potsdam (Germany)

[#]Authors contributed equally

[‡] Present address: The Centre for Research on Adaptive Nanostructures and Nanodevices, Trinity College Dublin, Dublin 2, Ireland

School of Physics, Trinity College Dublin, Dublin 2, Ireland

[§] Present address: Institute of Materials Physics and Technology, Hamburg University of Technology, 21073 Hamburg, Germany.

⁺ Present address: BASF Advanced Chemicals Co. Ltd, 200137 Shanghai, China.



SI Figure 1. 500 MHz ¹H-NMR spectrum of cPEVA31D10 with assigned chemical shifts utilized for calculation of the average segment length of PE sequence. a: $-COOCH_3$ -(methylene protons near the carboxyl group, $\delta = 1.8$ ppm); b: -CH- (methylene protons near the carboxyl group, $\delta = 5.0$ ppm); c: -CH₂- (linear methylene protons, $\delta = 1.3$ -1.6 ppm). The solvent (toluene-d₈) appears at $\delta = 2.2$ and 7.1 ppm.



SI Figure 2: DSC thermograms of copolymer starting materials, PEVA20 (dashed black line), PEVA31 (dashed grey line) and crosslinked cPEVAs with different composition. cPEVA20D05 (solid black line), cPEVA20D10 (dotted black line), cPEVA20D20 (dash-dotted black line) and cPEVA31D05 (solid grey line), cPEVA31D10 (dotted grey line), and cPEVA31D20 (dash-dotted grey line) at heating and cooling rates of 20 K·min⁻¹.



SI Figure 3: a) Quantification of temperature-memory effect with schematic illustration of the TMCP and recovery module under stress-free conditions. The TMCP for programming of the cPEVAs consisted of the following steps: After preconditioning, the sample was heated to T_{high} and cooled to T_{deform} (step 1) leading to a partial crystallization of the domains depending on the applied T_{deform} . In the step 2 the sample was deformed to ε_{m} at T_{deform} , and was held isothermally for 10 min under constant strain to allow structural reorganization of the fixing segments (step 3). In step 4, the sample was cooled to $T_{\text{low}} = 0$ °C under constant strain conditions and held isothermally for 10 min. Then in step 5, the stress was released to $\sigma = 0$ MPa at T_{low} , and the fixed temporary shape ε_{u} was obtained. For the shape recovery the specimen was reheated to T_{high} under stress-free conditions leading to step 6.

b) Temperature-memory effect. Stress-temperature-strain curves obtained from cyclic, thermomechanical tensile tests for cPEVA20D10 with stress-free recovery at various deformation temperatures: $T_{deform} = 10$ °C (green), 25 °C (blue), 40 °C (pink), 65 °C (light blue) and 90 °C (red). Fixed parameters: $T_{low} = 0$ °C, $T_{high} = 100$ °C, and $\varepsilon_m = 150\%$.



SI Figure 4: Equatorial section of the wide-angle scattering patterns of cPEVA31D20 following the temperature-memory effect (**a-h**) during TMCP. Left: $T_{\text{low}} = 10 \text{ °C}$ and $\varepsilon = 0\%$; **a-d**: T_{deform} (as indicated) and $\varepsilon_{\text{m}} = 150\%$; **e-h**: $T_{\text{low}} = 10 \text{ °C}$ and ε_{u} (temporary shape); **i** and **j**: Azimuthal profiles of the (110) diffraction from: in **i**: non-deformed (black), **a** (red), **b** (orange), **c** (dark cyan) and **d** (blue); in **j**) non-deformed (black), **e** (red), **f** (orange), **g** (dark cyan) and **h** (blue).

	Stress-free recovery						
Sample ID	T _{deform} ^a [°C]	$\sigma(\varepsilon_{\rm m})^{\rm b}$ [MPa]	<i>R</i> _f ^c [%]	<i>R</i> _r ^d [%]	T _{sw} ^e [°C]		
	90	0.26	104	100	89		
cPEVA20D05	65	1.81	97	98	69		
	40	3.75	83	97	43		
	25	4.62	74	99	28		
	10	5.80	53	100	16		
	90	0.42	101	100	87		
	65	1.95	103	100	68		
cPEVA20D10	40	4.31	84	100	43		
	25	5.60	74	99	31		
	10	7.02	51	100	16		
	90	0.85	100	100	79		
	65	1.94	97	99	68		
cPEVA20D20	40	4.49	83	99	44		
	25	5.36	75	99	36		
	10	7.32	52	100	23		

SI Table 1: Temperature-memory properties of the cPEVA20 series.

a) T_{deform} and fixed parameters: $T_{\text{low}} = 0$ °C, $T_{\text{high}} = 100$ °C, heating rate = 2 K·min⁻¹, cooling rate = 5 K·min⁻¹ and $\varepsilon_{\text{m}} = 150\%$; **b**) $\sigma(\varepsilon_{\text{m}})$: stress at ε_{m} ; **c**) R_{f} : shape fixity rate; **d**) R_{r} : shape recovery rate; **e**) T_{sw} : switching temperature.

	Stress-free recovery					
Sample ID	T _{deform} ^a [°C]	$\sigma(\varepsilon_{\rm m})^{\rm b}$ [MPa]	<i>R</i> _f ^c [%]	<i>R</i> _r ^d [%]	<i>T</i> _{sw} ^e [°C]	
	70	0.38	116	96	71	
	55	0.66	106	97	60	
cPEVA31D05	40	1.67	92	96	41	
	25	2.48	82	99	26	
	10	3.51	62	87	12	
cPEVA31D10	70	0.61	110	99	68	
	55	0.82	105	98	60	
	40	2.17	90	98	41	
	25	3.17	79	100	26	
	10	4.48	57	100	14	
cPEVA31D20	70	0.91	106	100	66	
	55	0.93	102	98	61	
	40	2.35	89	98	42	
	25	3.41	78	99	28	
	10	4.78	58	96	12	

SI Table 2: Temperature-memory properties of the cPEVA31 series.

a) T_{deform} and fixed parameters: $T_{\text{low}} = 0$ °C, $T_{\text{high}} = 80$ °C, heating rate = 2 K·min⁻¹, cooling rate = 5 K·min⁻¹ and $\varepsilon_{\text{m}} = 150\%$; **b**) $\sigma(\varepsilon_{\text{m}})$: stress at ε_{m} ; **c**) R_{f} : shape fixity rate; **d**) R_{r} : shape recovery rate; **e**) T_{sw} : switching temperature.